

## FEATURES

- | Size Design  $\Phi 8.0 \times 10.0 \text{mm}$

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- | High Current Handling Capability 10,000A @ 8/20  $\mu\text{s}$

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- | Low Capacitance and Insertion Loss

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- | Quick Response and Long Service Life

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- | Moisture sensitivity level: Level 1


 $\Phi 8.0 \times 10.0 \text{mm}$ 

## APPLICATION INFORMATION

- | Communication equipment.

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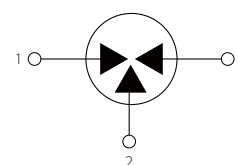
- | Repeaters, Modems

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- | Telephone Interface, Line cards.



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- | Data communication equipment.



Schematic Symbol

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)	100V/s	120-180	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq$ 650	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq$ 600	V
Impulse Discharge Current 2)	8/20 $\mu$ s	10	KA
Insulation Resistance	DC=50V	$\geq$ 1	G $\Omega$
Capacitance at 1MHz	V <sub>DC</sub> =0.5V	$\leq$ 2	pF
Operating and Storage Temperature		-40~125	$^{\circ}$ C

1) In ionized mode

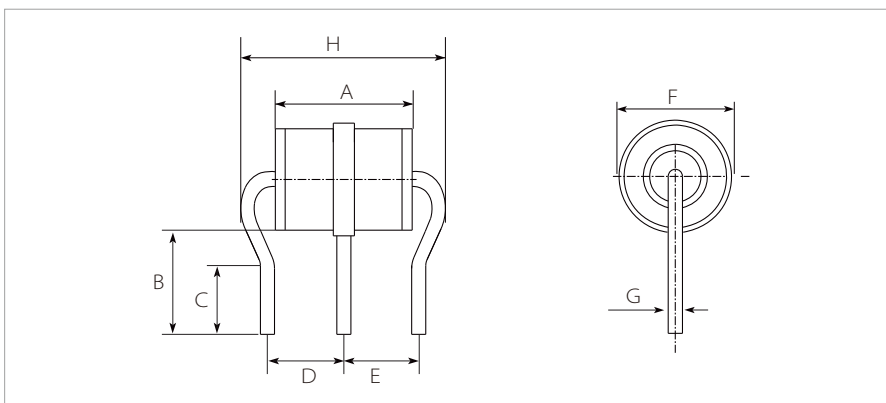
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $^{\circ}$ C; Time of dip soldering: 10s,1time

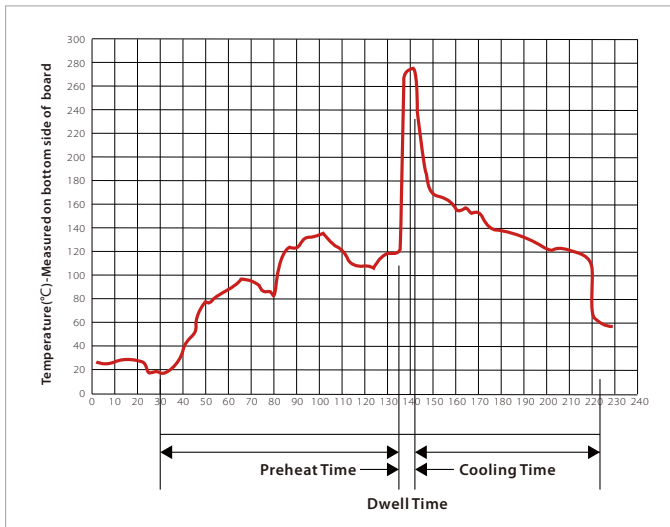
**NOTE:** Up-screen program can be specified by customer's request via contacting Semiware service

## PRODUCT DIMENSIONS




Ref.	Outline Dimensions
	Millimeters
A	10 $\pm$ 0.3
B	7.0 $\pm$ 0.5
C	4.0 $\pm$ 0.5
D	4.4 $\pm$ 0.3
E	4.4 $\pm$ 0.3
F	$\Phi$ 8.0 $\pm$ 0.2
G	$\Phi$ 1.0
H	13 $\pm$ 1

## WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

## ORDERING INFORMATION

Part Number	Size	Marking	Qty/pcs		
			Tray	Inner Box	Carton
SG3R08B150	Ø8.0*10.0mm	 SG150 08	100	500	6000

**Headquarters**

No.3387 Shendu Road Pujiang  
I&E Park  
Minhang Shanghai China  
201000

**Hotline**

400-021-5756

**Web**

<https://www.semiware.com>

**Sales Center**

Tel: 86-21-3463-7458  
Email: [sales18@semiware.com](mailto:sales18@semiware.com)

**Customer Service**

Tel: 86-21-5484-1001  
Email: [sales17@semiware.com](mailto:sales17@semiware.com)

**Technical Support**

Tel: 86-21-3463-7654  
Email: [fae01@semiware.com](mailto:fae01@semiware.com)

**Complaint & Suggestions**

Tel: 86-21-3463-7172  
Ext: 8868  
Email: [cs03@semiware.com](mailto:cs03@semiware.com)

**By QR Code**

Website



Wechat

To find your local partner within Semiware's global network: [www.semiware.com](http://www.semiware.com)

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